Title (en)

use of compositions for eliminating silicon compounds

Title (de)

Verwendung von Zusammensetzungen zur Entfernung von Silikonverbindungen

Title (fr)

usage des compositions pour eliminer des composes de silicone

Publication

EP 1739162 A1 20070103 (DE)

Application

EP 05105954 A 20050630

Priority

EP 05105954 A 20050630

Abstract (en)

Use of a composition comprising at least one substrate and at least one silicic acid and/or at least one silicate, for removing impurities, preferably silicon compounds from a glass or a glass ceramic surface. Independent claims are included for: (1) a method for gluing two substrates, comprising cleaning the surface of the two substrates by using the composition, applying the adhesive on the surface of the two substrates, contacting the surface of the second substrate with the adhesive, which is located on the first substrates or contacting the surface of the first substrate with the adhesive, which is located on the second substrates, and hardening the adhesive by precipitation; and (2) the composition comprising at least one fiber material and at least one silicic acid and/or at least one silicate.

IPC 8 full level

C11D 3/12 (2006.01); **C11D 3/16** (2006.01); **C11D 3/43** (2006.01); **C11D 7/14** (2006.01); **C11D 11/00** (2006.01); **C11D 17/04** (2006.01)

CPC (source: EP US)

C11D 7/14 (2013.01 - EP US); C11D 2111/18 (2024.01 - EP US); Y10T 156/10 (2015.01 - EP US)

Citation (search report)
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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR LV MK YU

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DOCDB simple family (application)

EP 05105954 A 20050630; EP 2006063710 W 20060630; JP 2008518855 A 20060630; US 92291406 A 20060630